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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





ZXTP722MA

70V PNP LOW SATURATION TRANSISTOR

Features and Benefits

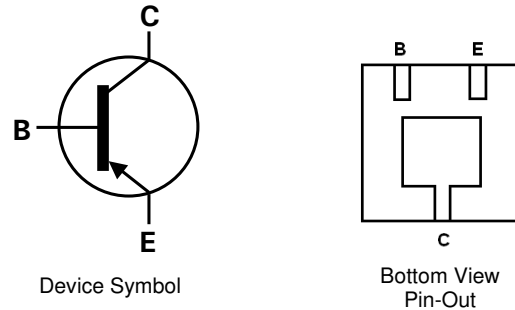
- $BV_{CEO} > -70V$
- $I_C = -2.5A$ Continuous Collector Current
- Low Saturation Voltage (-220mV max @ -1A)
- $R_{SAT} = 117\ m\Omega$ for a low equivalent On-Resistance
- h_{FE} specified up to -3A for high current gain hold up
- Low profile 0.6mm high package for thin applications
- $R_{\theta JA}$ efficient, 60% lower than SOT23
- 4mm² footprint, 50% smaller than SOT23
- **Lead-Free, RoHS Compliant (Note 1)**
- **Halogen and Antimony Free. "Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: DFN2020B-3
- Case material: Molded Plastic. "Green" Molding Compound.
- Terminals: Pre-Plated NiPdAu leadframe.
- Nominal package height: 0.6mm
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.01 grams (approximate)

Applications

- MOSFET Gate Driving
- DC-DC Converters
- Charging Circuits
- Power switches
- Motor control

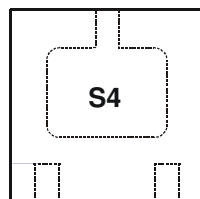


Ordering Information

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP722MATA	S4	7	8	3000

- Notes:
1. No purposefully added lead.
 2. Diodes Inc's "Green" policy can be found on our website at <http://www.diodes.com>

Marking Information



Top View

S4 = Product Type Marking code

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

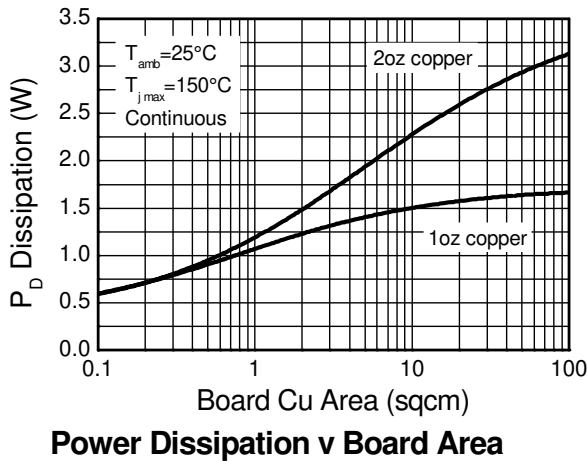
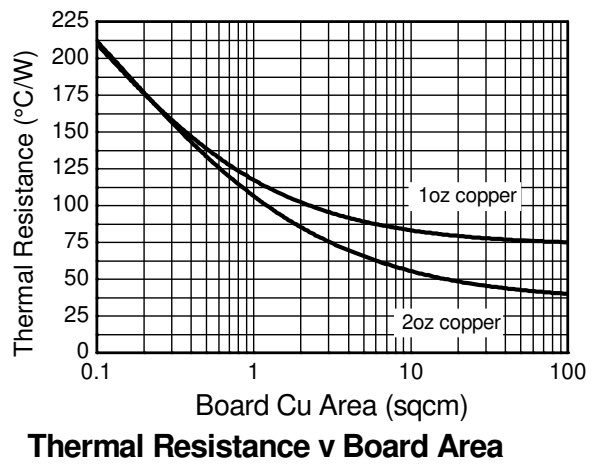
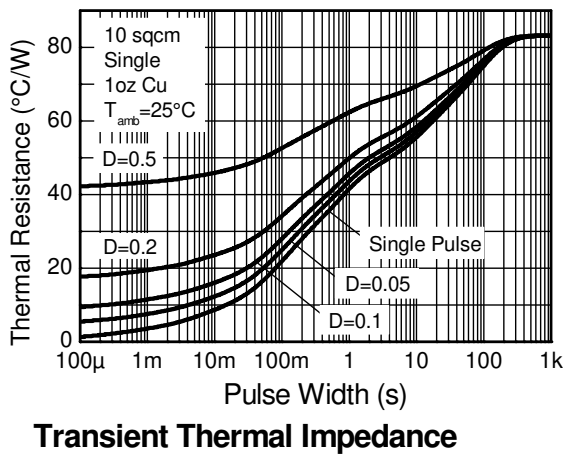
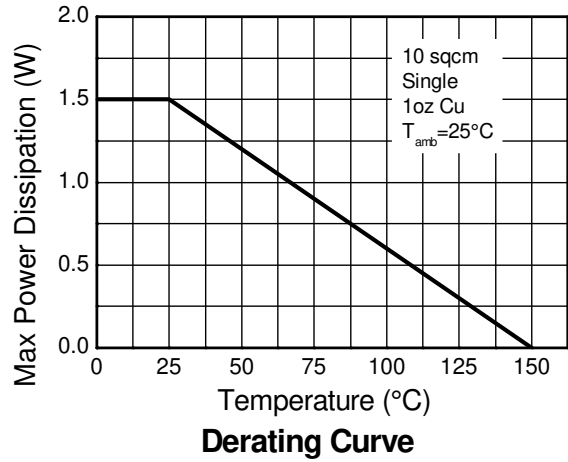
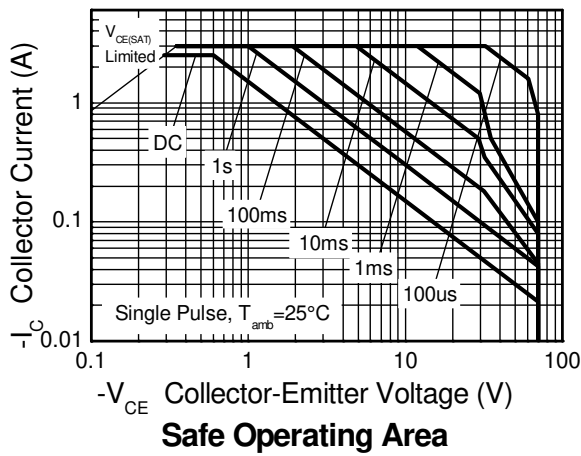
Characteristic		Symbol	Value	Unit
Collector-Base Voltage		V_{CBO}	-70	V
Collector-Emitter Voltage		V_{CEO}	-70	
Emitter-Base Voltage		V_{EBO}	-7	
Peak Pulse Current		I_{CM}	-3	A
Continuous Collector Current	(Note 3)	I_C	-2.5	
	(Note 4)		-2.7	
Base Current		I_B	-1	

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 3)	P_D	1.5	W mW/ $^\circ\text{C}$
			12	
	(Note 4)		2.45 19.6	
Thermal Resistance, Junction to Ambient	(Note 3)	$R_{\theta JA}$	83	$^\circ\text{C}/\text{W}$
	(Note 4)		51	
Thermal Resistance, Junction to Lead	(Note 5)	$R_{\theta JL}$	16.8	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

- Notes:
3. For a device surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The entire exposed collector pad is attached to the heatsink.
 4. Same as note (3), except the device is measured at $t \leq 5$ sec.
 5. For a single device, thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics

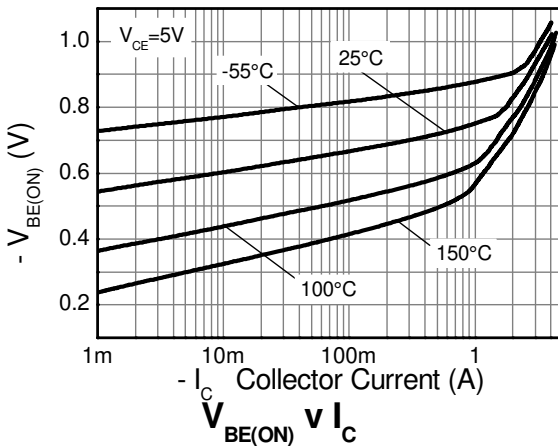
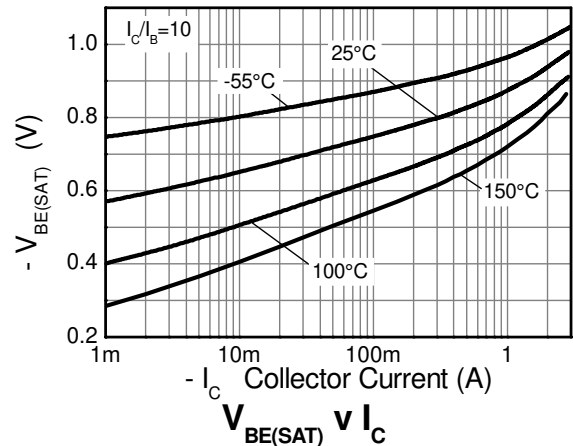
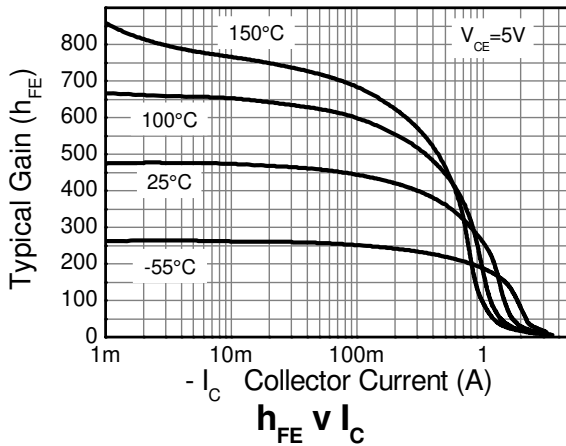
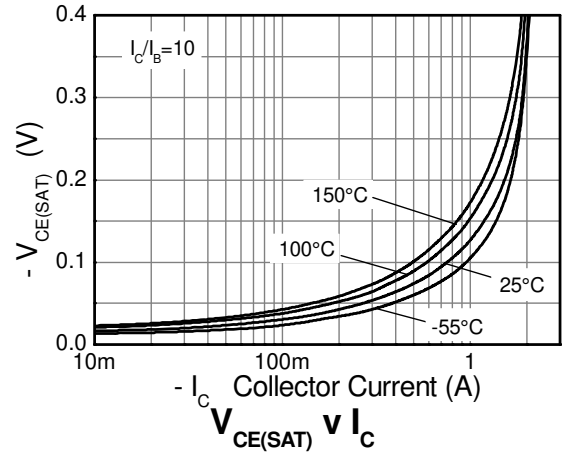
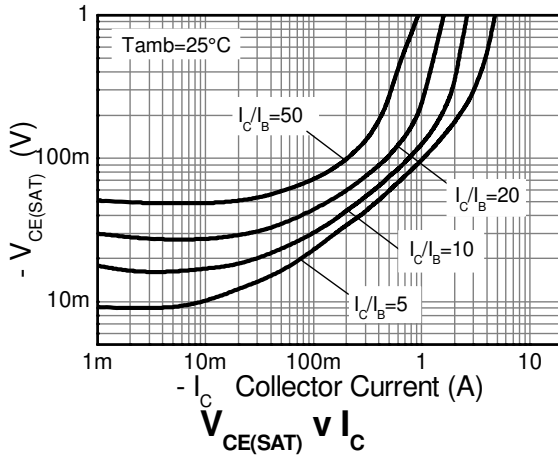


Electrical Characteristics @T_A = 25°C unless otherwise specified

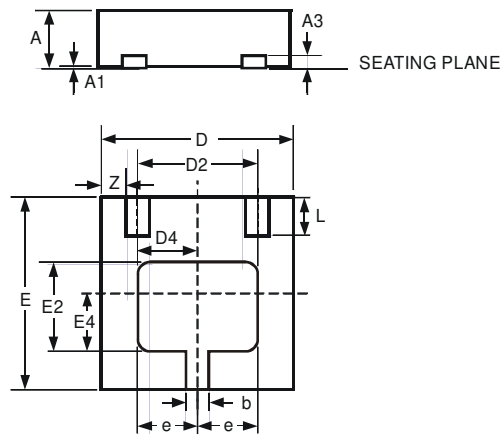
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-70	-150	-	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 6)	BV _{CEO}	-70	-125	-	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.5	-	V	I _E = -100μA
Collector Cutoff Current	I _{CBO}	-	-	-100	nA	V _{CB} = -55V
Emitter Cutoff Current	I _{EBO}	-	-	-100	nA	V _{EB} = -6V
Collector Emitter Cutoff Current	I _{CES}	-	-	-100	nA	V _{CES} = -55V
Static Forward Current Transfer Ratio (Note 6)	h _{FE}	300	470	-	-	I _C = -10mA, V _{CE} = -5V
		300	450	-		I _C = -100mA, V _{CE} = -5V
		175	275	-		I _C = -1A, V _{CE} = -5V
		40	60	-		I _C = -1.5A, V _{CE} = -5V
		-	10	-		I _C = -3A, V _{CE} = -5V
Collector-Emitter Saturation Voltage (Note 6)	V _{CE(sat)}	-	-35	-50	mV	I _C = -0.1A, I _B = -10mA
		-	-135	-200		I _C = -0.5A, I _B = -20mA
		-	-140	-220		I _C = -1A, I _B = -100mA
		-	-175	-270		I _C = -1.5A, I _B = -200mA
Base-Emitter Turn-On Voltage (Note 6)	V _{BE(on)}	-	-0.78	-1.00	V	I _C = -1.5A, V _{CE} = -5V
Base-Emitter Saturation Voltage (Note 6)	V _{BE(sat)}	-	-0.94	-1.05	V	I _C = -1.5A, I _B = -200mA
Output Capacitance	C _{obo}	-	14	20	pF	V _{CB} = -10V, f = 1MHz
Transition Frequency	f _T	150	180	-	MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz
Turn-On Time	t _{on}	-	40	-	ns	V _{CC} = -50V, I _C = -1A
Turn-Off Time	t _{off}	-	700	-	ns	I _{B1} = I _{B2} = -50mA

Notes: 6. Measured under pulsed conditions. Pulse width ≤ 300 μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics

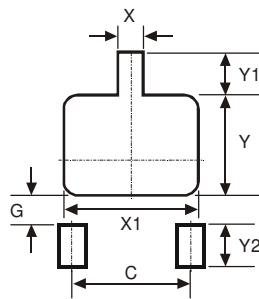


Package Outline Dimensions



DFN2020B-3			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0	0.05	0.02
A3	—	—	0.152
b	0.20	0.30	0.25
D	1.95	2.075	2.00
D2	1.22	1.42	1.32
D4	0.56	0.76	0.66
e	—	—	0.65
E	1.95	2.075	2.00
E2	0.79	0.99	0.89
E4	0.48	0.68	0.58
L	0.25	0.35	0.30
Z	—	—	0.225
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	1.30
G	0.24
X	0.35
X1	1.52
Y	1.09
Y1	0.47
Y2	0.50

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